

PolarHT™ HiPerFET Power MOSFET

N-Channel Enhancement Mode
Fast Intrinsic Diode
Avalanche Rated

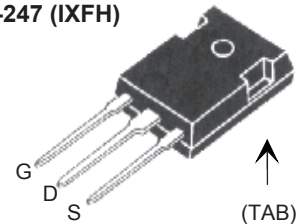
IXFH 110N10P
IXFV 110N10P
IXFV 110N10PS

$V_{DSS} = 100 \text{ V}$
 $I_{D25} = 110 \text{ A}$
 $R_{DS(on)} \leq 15 \text{ m}\Omega$
 $t_{rr} \leq 150 \text{ ns}$

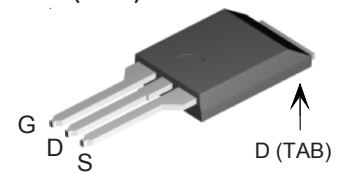


| Symbol | Test Conditions | Maximum Ratings | |
|--------------|---|------------------|------------------|
| | | | |
| V_{DSS} | $T_J = 25^\circ\text{C to } 175^\circ\text{C}$ | 100 | V |
| V_{DGR} | $T_J = 25^\circ\text{C to } 175^\circ\text{C}; R_{GS} = 1 \text{ M}\Omega$ | 100 | V |
| V_{GSS} | Continuous | ± 20 | V |
| V_{GSM} | Transient | ± 30 | V |
| I_{D25} | $T_C = 25^\circ\text{C}$ | 110 | A |
| $I_{D(RMS)}$ | External lead current limit | 75 | A |
| I_{DM} | $T_C = 25^\circ\text{C}$, pulse width limited by T_{JM} | 250 | A |
| I_{AR} | $T_C = 25^\circ\text{C}$ | 60 | A |
| E_{AR} | $T_C = 25^\circ\text{C}$ | 40 | mJ |
| E_{AS} | $T_C = 25^\circ\text{C}$ | 1.0 | J |
| dv/dt | $I_S \leq I_{DM}$, $di/dt \leq 100 \text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DSS}$, $T_J \leq 150^\circ\text{C}$, $R_G = 4 \Omega$ | 10 | V/ns |
| P_D | $T_C = 25^\circ\text{C}$ | 480 | W |
| T_J | | -55 ... +175 | $^\circ\text{C}$ |
| T_{JM} | | 175 | $^\circ\text{C}$ |
| T_{stg} | | -55 ... +150 | $^\circ\text{C}$ |
| T_L | 1.6 mm (0.062 in.) from case for 10 s | 300 | $^\circ\text{C}$ |
| T_{SOLD} | Plastic body for 10 s | 260 | $^\circ\text{C}$ |
| M_d | Mounting torque (TO-247) | 1.13/10 | Nm/lb.in. |
| F_C | Mounting Force (PLUS220) | 11..65 / 2.5..15 | N/lb |
| Weight | TO-247 | 6 | g |
| | PLUS220 | 4 | g |

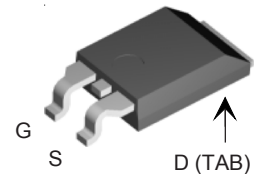
TO-247 (IXFH)



PLUS220 (IXFV)



PLUS220SMD (IXFV...S)



G = Gate D = Drain
S = Source TAB = Drain

Features

- † Fast intrinsic diode
- † International standard packages
- † Unclamped Inductive Switching (UIS) rated
- † Low package inductance
- easy to drive and to protect

Advantages

- † Easy to mount
- † Space savings
- † High power density

| Symbol | Test Conditions ($T_J = 25^\circ\text{C}$, unless otherwise specified) | Characteristic Values | | |
|--------------|--|-----------------------|------|----------------------|
| | | Min. | Typ. | Max. |
| BV_{DSS} | $V_{GS} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$ | 100 | | V |
| $V_{GS(th)}$ | $V_{DS} = V_{GS}$, $I_D = 4 \text{ mA}$ | 2.5 | | 5.0 V |
| I_{GSS} | $V_{GS} = \pm 20 \text{ V}_{DC}$, $V_{DS} = 0$ | | | $\pm 100 \text{ nA}$ |
| I_{DSS} | $V_{DS} = V_{DSS}$ | | | 25 μA |
| | $V_{GS} = 0 \text{ V}$ $T_J = 150^\circ\text{C}$ | | | 250 μA |
| $R_{DS(on)}$ | $V_{GS} = 10 \text{ V}$, $I_D = 0.5 I_{D25}$ Pulse test, $t \leq 300 \mu\text{s}$, duty cycle $d \leq 2 \%$ | | | 15 $\text{m}\Omega$ |

Fig. 1. Output Characteristics @ 25°C

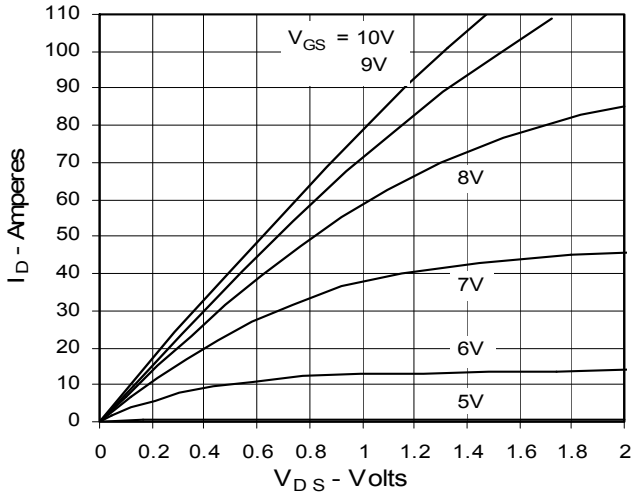


Fig. 2. Extended Output Characteristics @ 25°C

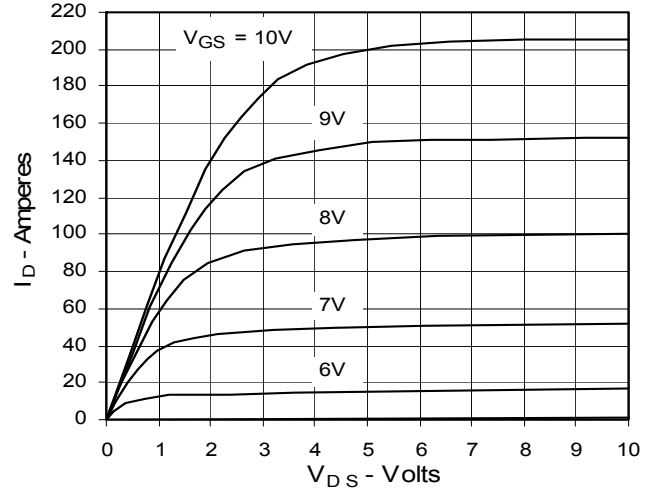


Fig. 3. Output Characteristics @ 150°C

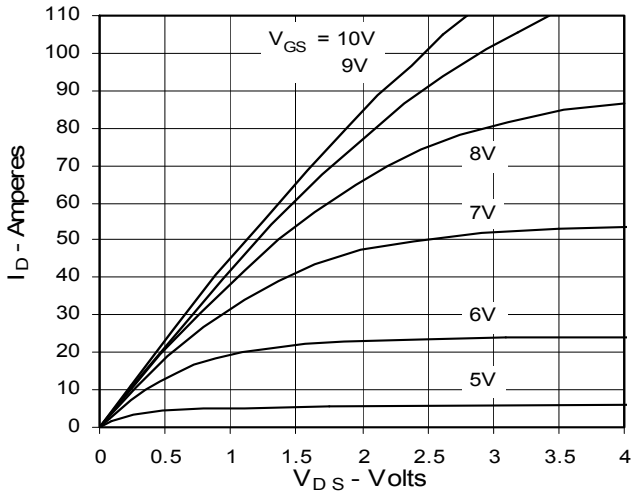


Fig. 4. $R_{DS(on)}$ Normalized to 0.5 I_{D25} Value vs. Junction Temperature

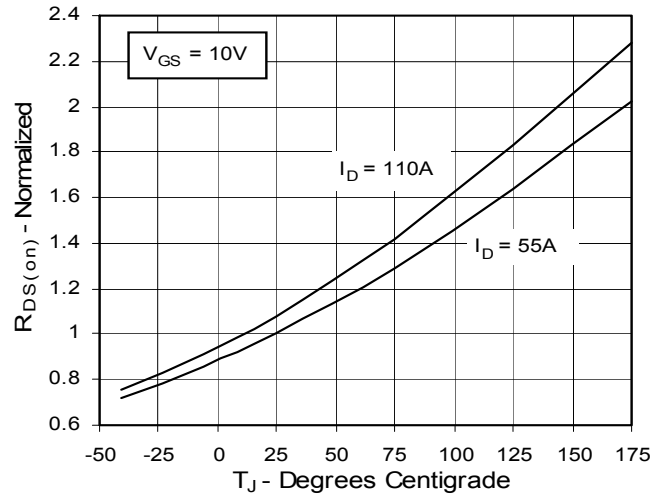


Fig. 5. $R_{DS(on)}$ Normalized to 0.5 I_{D25} Value vs. Drain Current

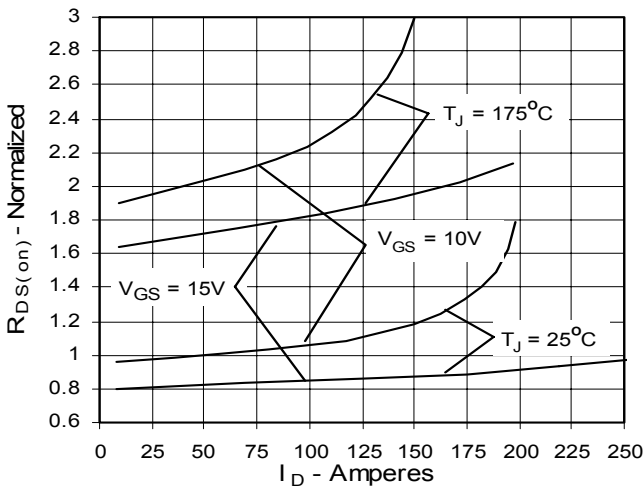


Fig. 6. Drain Current vs. Case Temperature

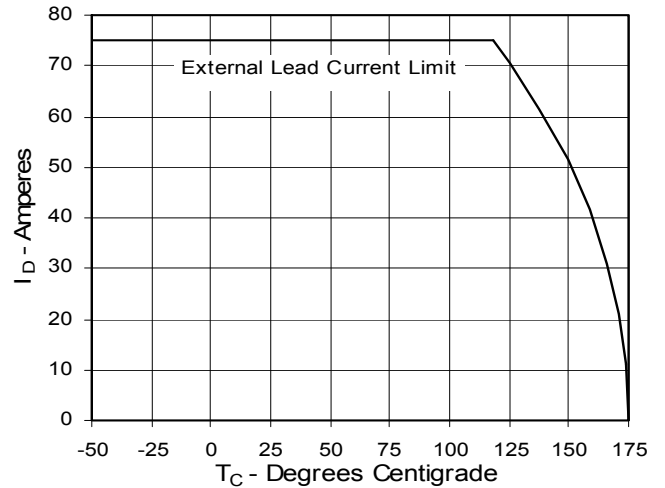


Fig. 7. Input Admittance

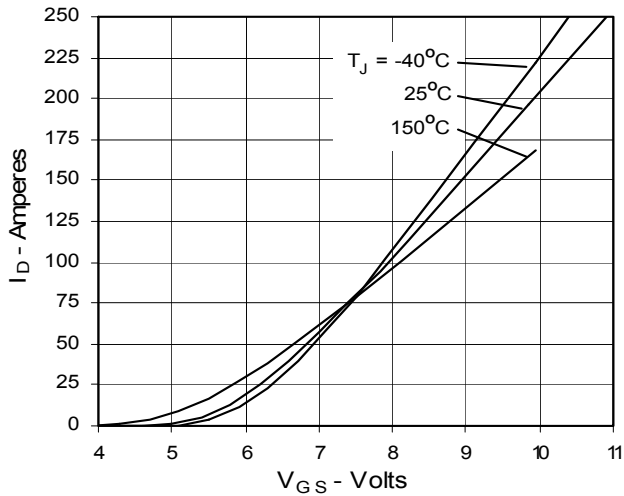


Fig. 8. Transconductance

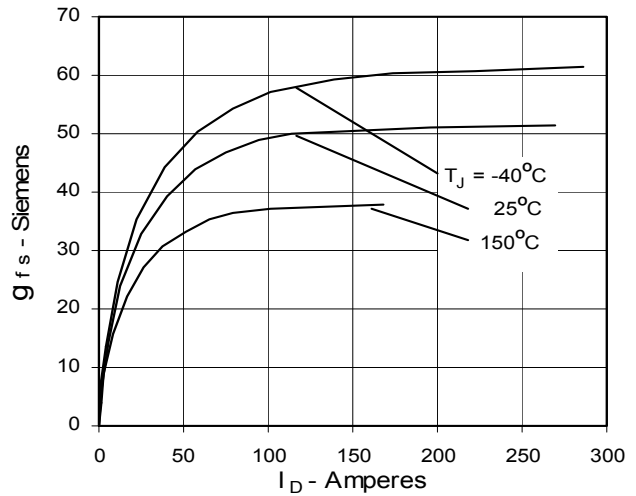


Fig. 9. Source Current vs. Source-To-Drain Voltage

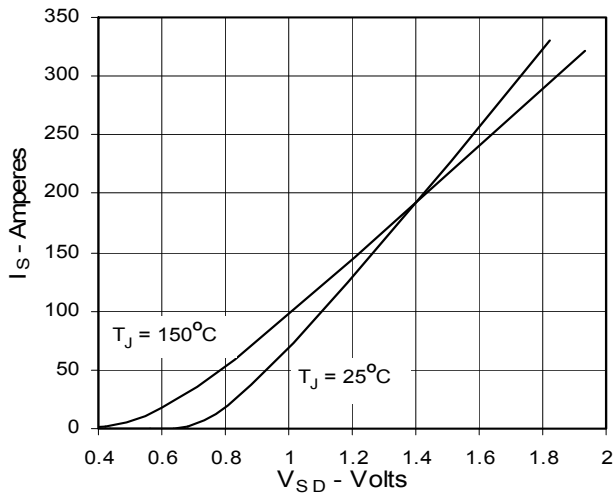


Fig. 10. Gate Charge

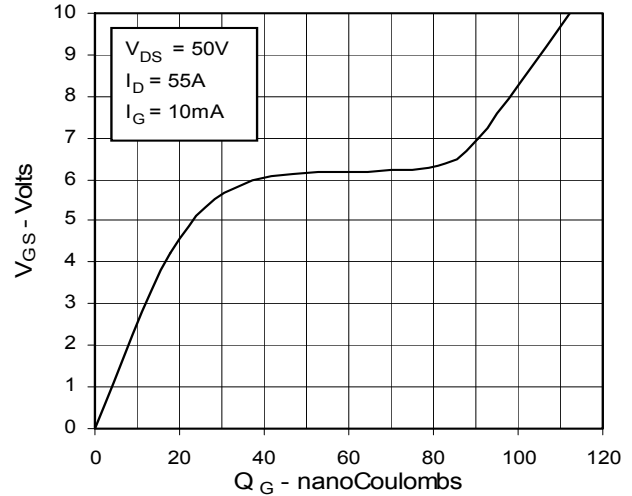


Fig. 11. Capacitance

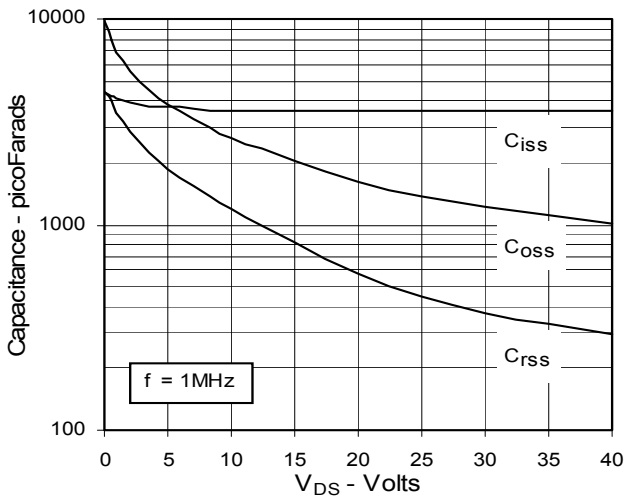


Fig. 12. Forward-Bias Safe Operating Area

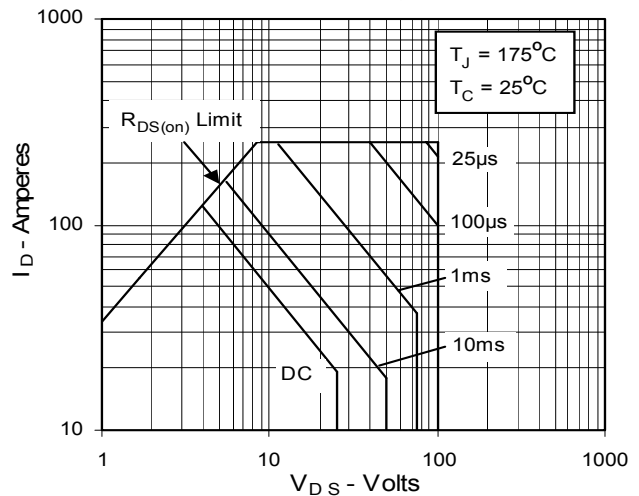


Fig. 13. Maximum Transient Thermal Resistance

